

# FPGA 2032 Roadmap : A Personal Perspective

# Learn from Yesterday

2012



1992



Blackberry

Courtesy : Don McMillan

# Learn from Yesterday

2012



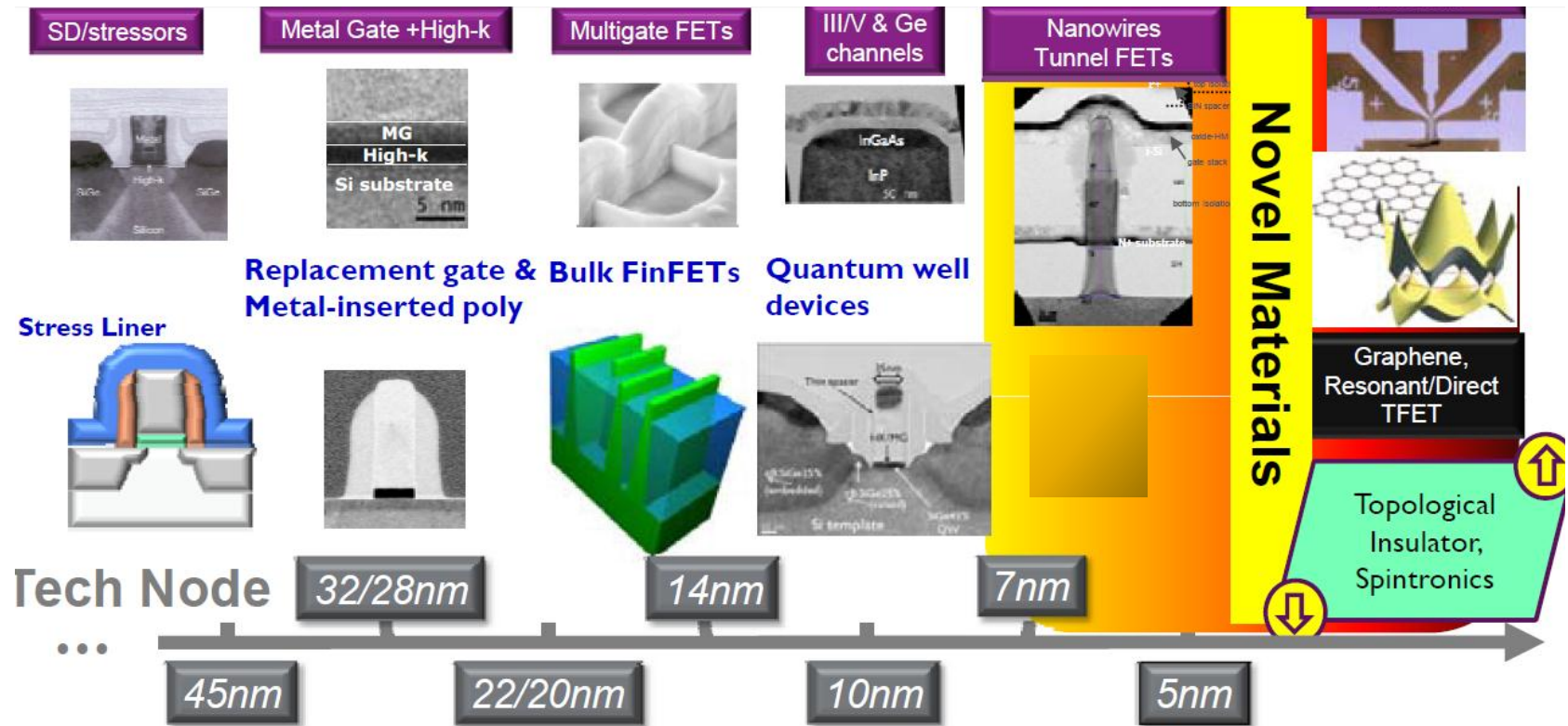
Courtesy : Don McMillan

1972



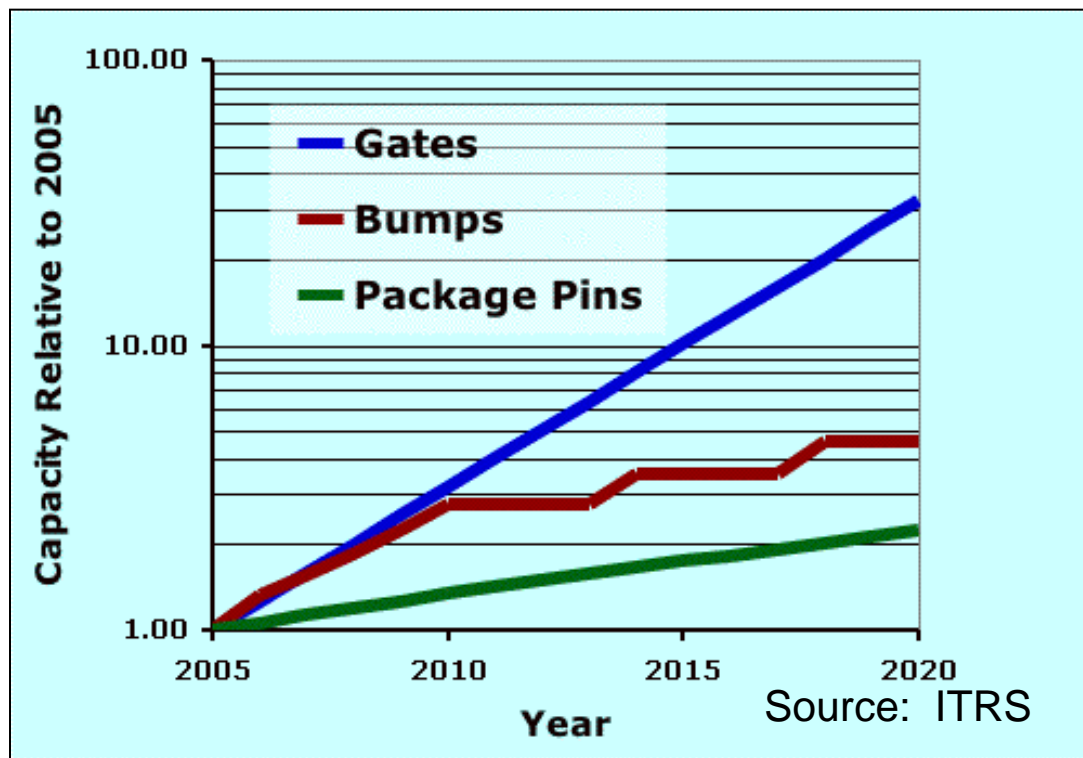
## Cell Phone

# Silicon Roadmap



# Interconnect

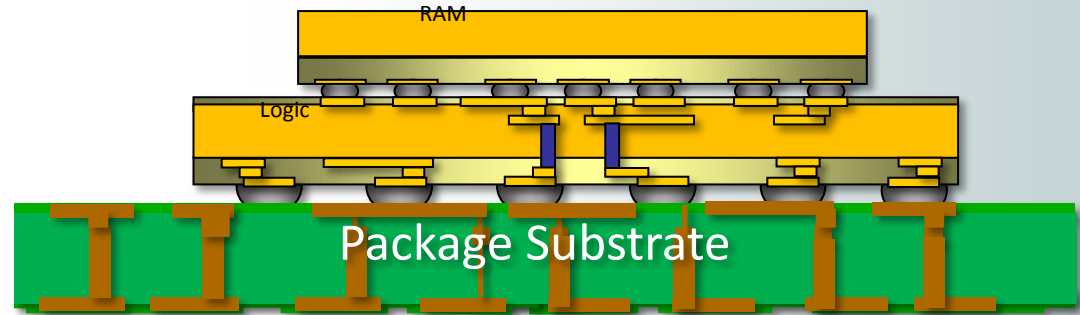
- Growing gap between number of logic gates and I/O
- Technology scaling favors logic density



*15x drop in  
I/O-to-logic ratio  
by 2020*

# What Does 2.5D and 3D Buy Us?

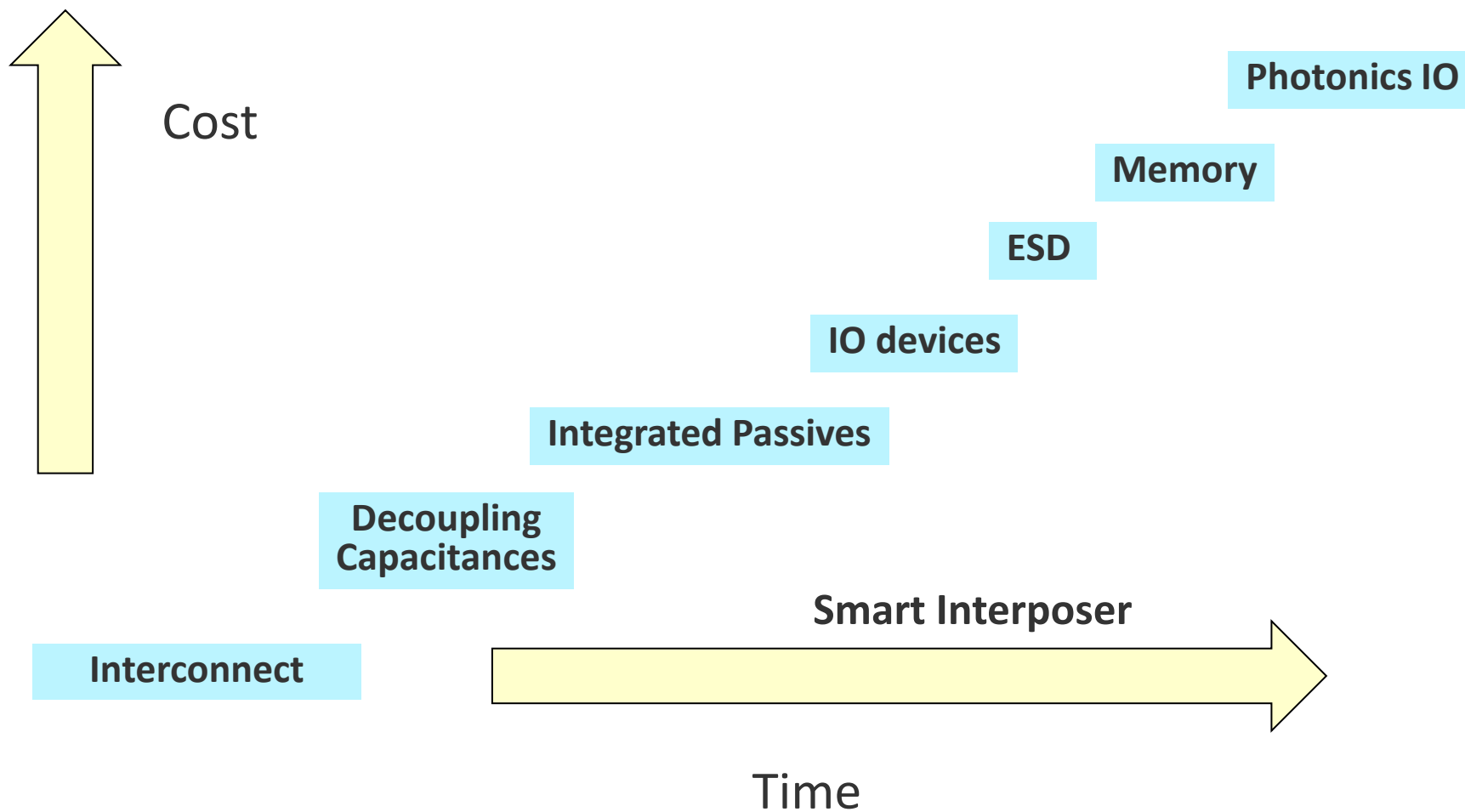
- **Connectivity**
- **Capacity**
- **Crossovers**



# 3D versus 2.5D

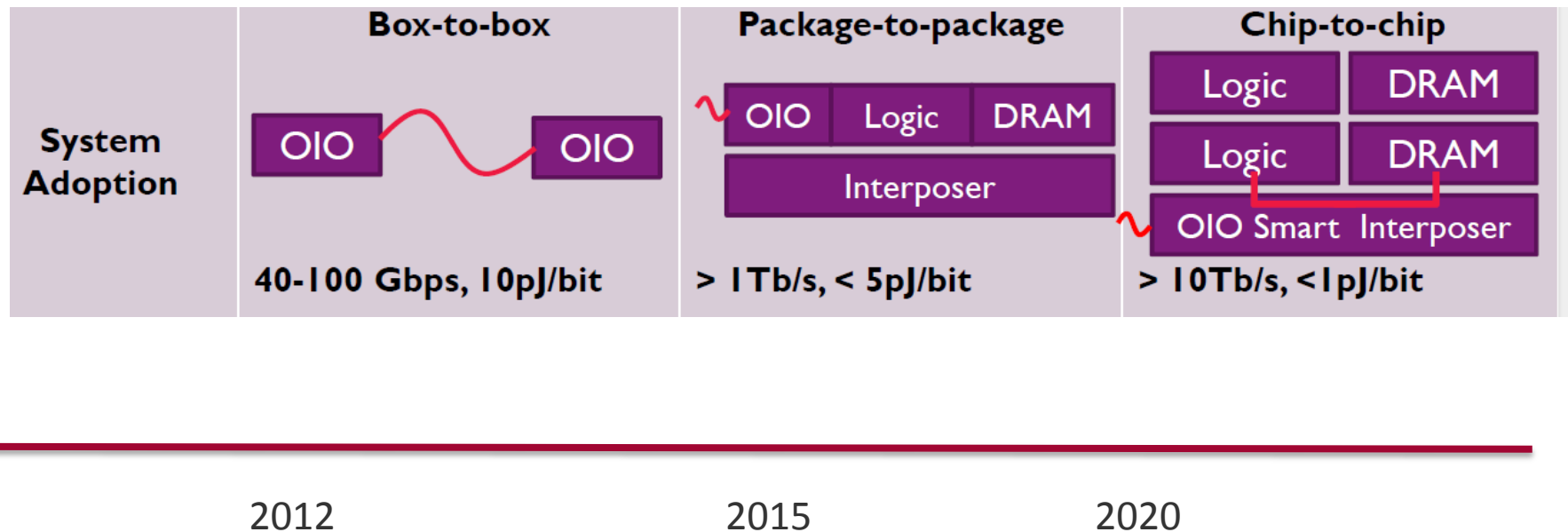
	3D	2.5D
Design Flow	New Co-Design	Evolutionary
Device impact	Stress	None
Cost	High	65nm Interposer
Thermal	Challenging	Evolutionary
Testing	New Methods	Evolutionary
Reliability	Challenging	Evolutionary

# 2.5D and 3D Interconnect





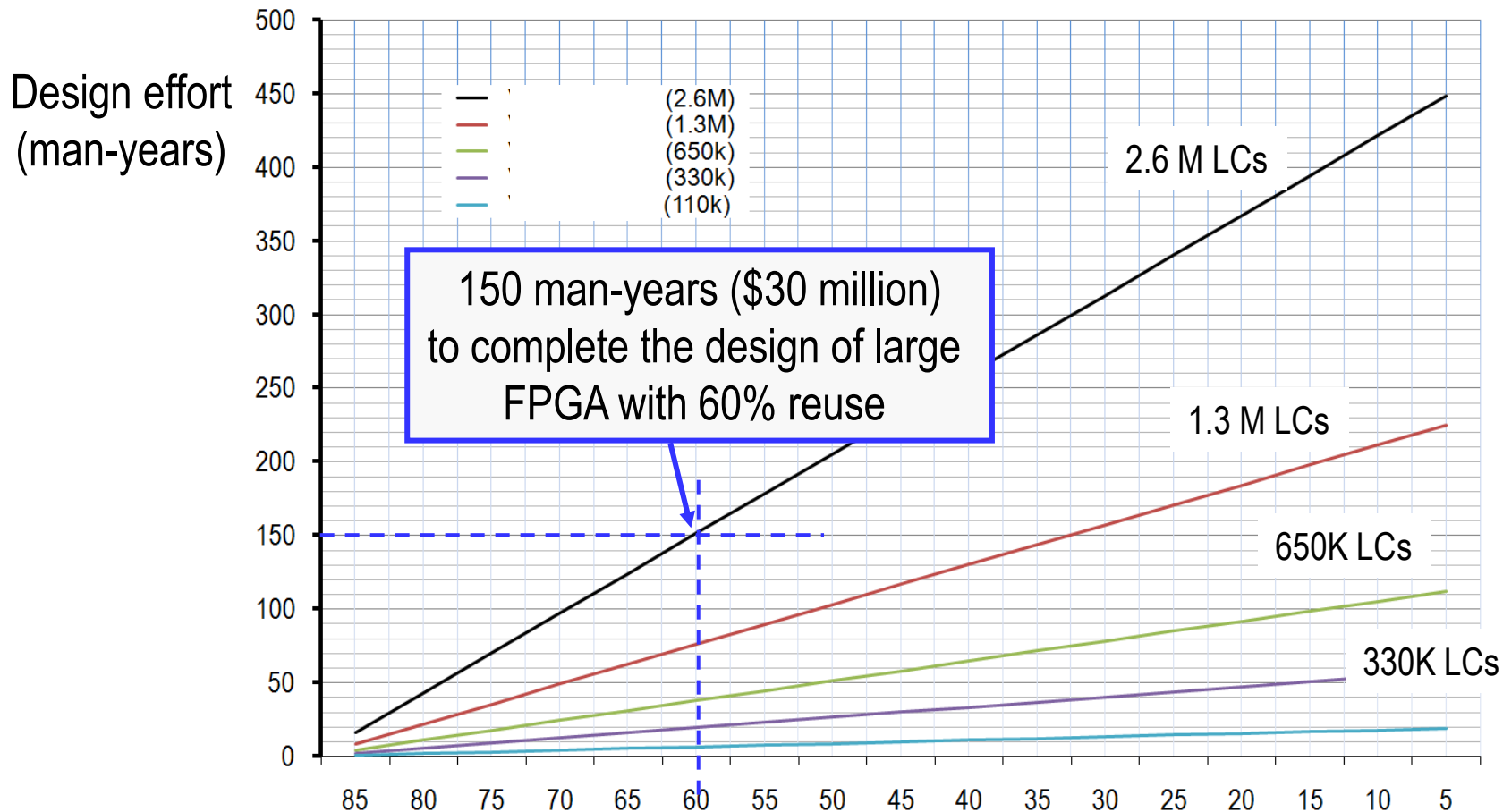
# Optical Interconnect



# ASIC Use Model

System Design	System design (function to microarchitecture) Per 5kLC core	1 man-week
New IP Design	New core creation (5kLC cores)	
	Design	15 man-weeks
New IP Verify	Verification	30 man-weeks
	Total	45 man-weeks
3rd party IP re-use (including Xilinx IP)	3rd-party Core Re-use (per core)	
	Assessment	7.5 man-weeks
	Verification	15 man-weeks
	Total	22.5 man-weeks
Legacy Design Port and Re-verify	Legacy core port to new device (per core)	
	Port	0.5 man-weeks
	Re-verify	1 man-weeks
	Total	1.5 man-weeks
System Integrate	Final system integration & verification (per core)	
	Core integration	0.5 man-weeks
System Verify	System verification	1 man-weeks
	Total	1.5 man-weeks

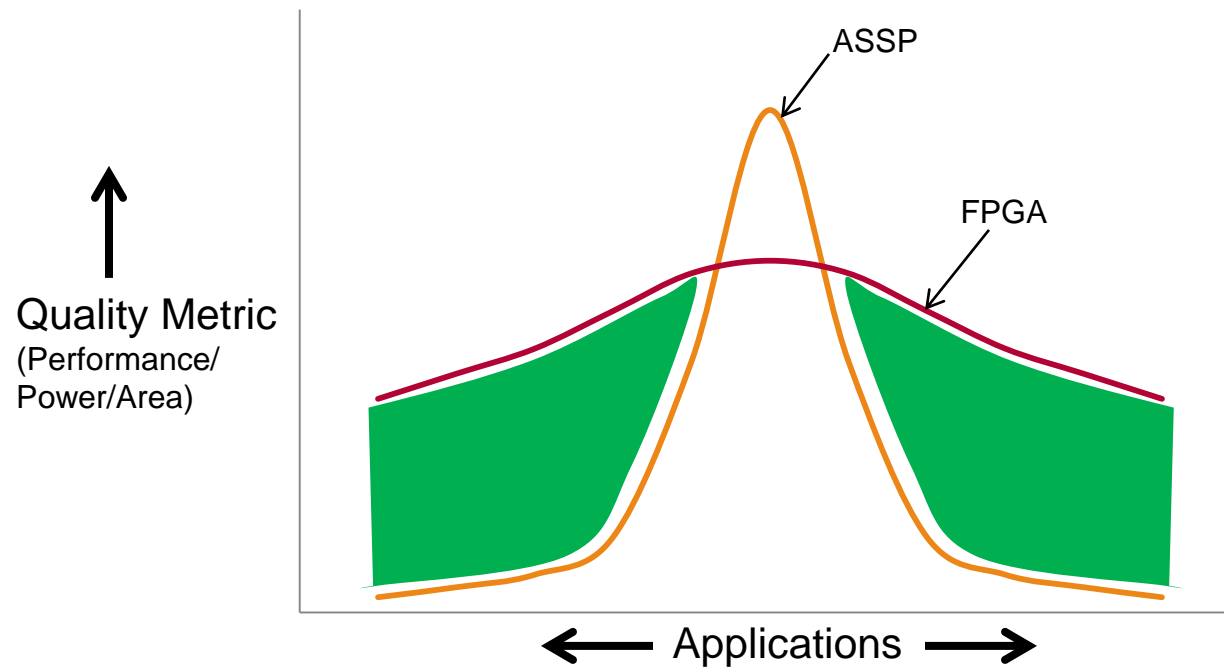
# Model of FPGA HW customer design effort



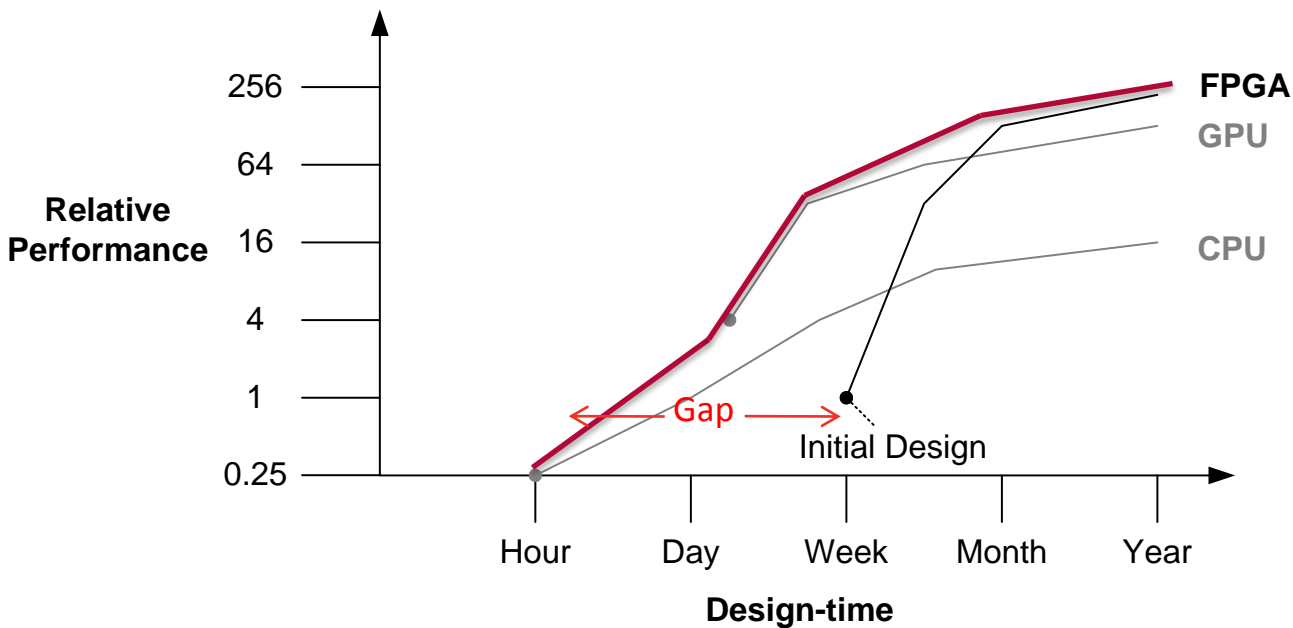
Note: maximum 85% device utilization is assumed

% design re-use (fabric only)

# SW Use Model : FPGA and Multi-core ASSP



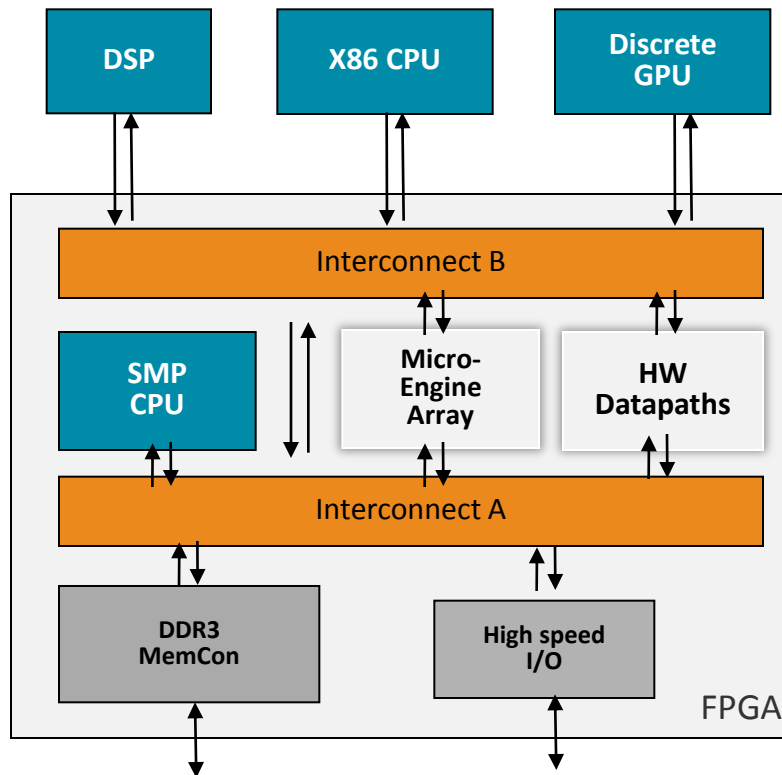
# Need for Design Tools



Courtesy : David Thomas

# The Programmable Processing Platform

A heterogeneous multicore



## ■ Application processors

- Hard core and soft core
- External and embedded
- Caches and large memory space
- Unified shared memory
- Full OS support

## ■ Streaming micro-engines

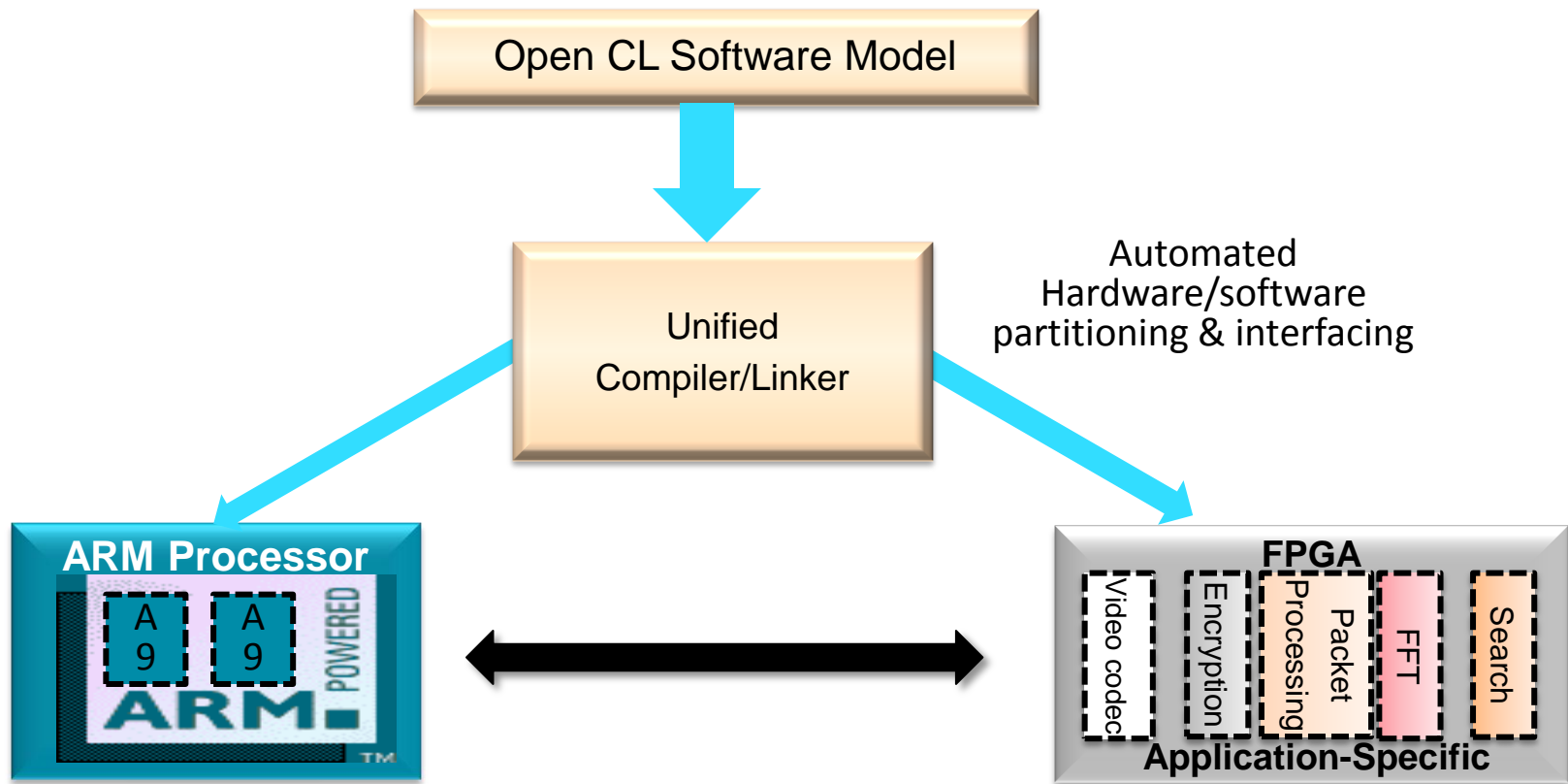
- Configurable (soft) vector cores
- Tiny memory footprint
- Many, distributed, memories
- Compute kernels, no OS

## ■ Fixed function datapaths

- C to Gates generated
- HDL coded
- Library IP component

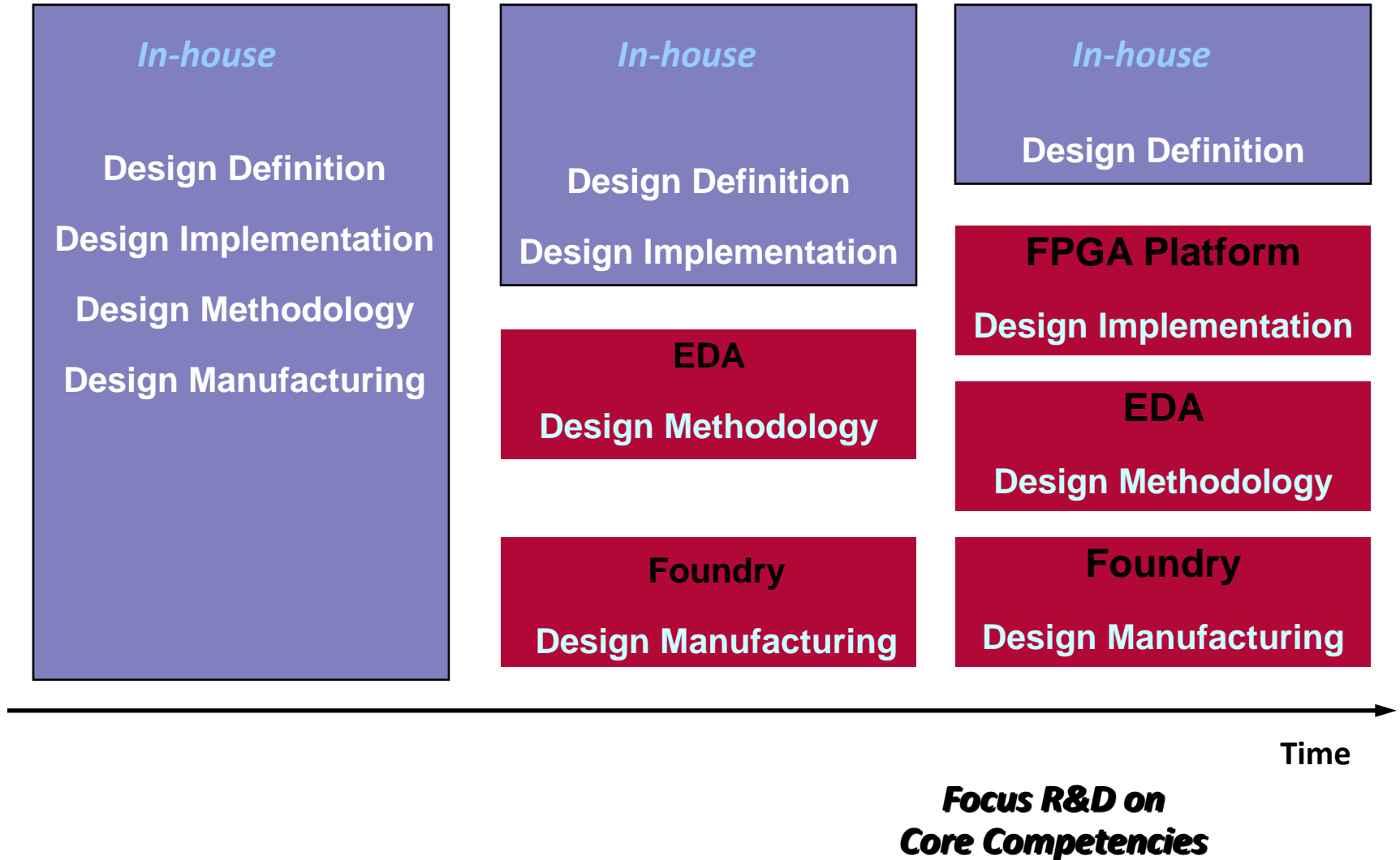
*FPGAs provide a rich set of mapping options for complex algorithms and communication patterns*

# Parallel Programming



**Application Level Programming of Heterogeneous Multi-core**

# The Design Stack





# Conclusions : 2032 FPGA

- Silicon Technology Roadmap continues

Challenges : Variability, Fault tolerance, Power limited, Cost

- 2.5 D and 3 D essential

Opportunity : Connectivity, Capacity, Heterogeneity

- HW Design Methods handle complexity

- Re-Use

- Modular Design Flow/Architecture + 10 min 1M LC P&R

- 33% utilization : dark silicon/fault tolerance

- Software Use Model

- Parallel programming

- Heterogeneous Multi-core

- Solve Timing Closure

# The Singularity



$10^{10}$  Transistors =  $10^{10}$  Neurons



Parallel Architecture



Synapse :  $10^3$  denser interconnect



Fault tolerant



Asynchronous



Adaptable



Content Addressable Memory



$10^7$  more energy efficient

